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<th>Item #</th>
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<th>Designator</th>
<th>Value</th>
<th>Description</th>
<th>Manufacturer</th>
<th>PartNumber</th>
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<td>C1, C3, C5, C6, C9, Copt</td>
<td>0.1uF</td>
<td>CAP, CERM, 0.1uF, 16V, +/-5%, X7R, 0603</td>
<td>AVX</td>
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<td>2</td>
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<td>MACHINE SCREW PAN PHILLIPS 4-40</td>
<td>B&amp;F Fastener Supply</td>
<td>PMSSS 440 0025 PH</td>
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